JL7006F Datasheet

Zhuhai Jieli Technology Co.,LTD

Version: 1.1

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JL7006F Features

CPU

- 32bit Dual-Issue DSP
- Up to 160MHz programmable processor
- With IEEE754 Single precision FPU
- With cordic accelerate engine
- Advanced debug with 8 hardware breakpoints/watchpoints
- Advanced system execption capture unit

Interrupt

- Support for up to 64 interrupts with 8 priority level
- NMI supported
- SWI supported, with configurable priority
- Low power wake up by polling pending 12 IO interrupts for low power wake up

DSP Audio Processing

- SBC, AAC Audio decodes supported for BT audio
- mSBC voice codec supported for BT phone
- Supports MP2, MP3, WMA, APE, FLAC, AAC, MP4, M4A, WAV, AIF, AIFC audio decoding
- Packet Loss Concealment (PLC) for voice processing
- Single/Dual MIC Environmental Noise Cancellation (ENC)
- Multi-band DRC limiter
- 20-band EQ configuration for voice Effects

Audio Codec

- Two channels 24-bit DAC, SNR >= 102dB
- Two channels 24-bit ADC, SNR >= 95dB
- DAC Sampling rates of 8kHz/11.025kHz/16kHz/22.05kHz/24kHz/32kHz/44.1kHz/48kHz/64kHz/88.2kHz/96kHz are supported
- ADC Sampling rates of 8kHz/11.025kHz/16kHz/22.05kHz/24kHz/32 kHz/44.1kHz/48kHz are supported

- Two analog MIC amplifier, build-in MIC bias generator
- Supports Four PDM digital MIC inputs
- Two channels analog AUX, supports stereo
- Supports cap-less, single-ended, and Two differential mode at the DAC path
- Supports 16ohm and 32ohm Speaker loading

ANC

- ANC processing engine up to 750 kHz sample rate
- * 7.5μs analog to analog latency
- Supports 4 digital microphone inputs, 2 differential or single-ended analog inputs for ANC
- Supports 2 channels Feed-Forward, Feed-Back, Hybrid ANC
- ANC module include 20 double precision
 Biquad filters for each FF/FB/ music
 compensation control

Bluetooth

- Compliant with Bluetooth
 V5.3+BR+EDR+BLE specification
- Meet class2 and class3 transmitting power requirement
- Support GFSK and DQPSK all packet types
- Provides maximum +10dbm transmitting power
- EDR receiver with minimum -94dBm sensitivity
- Fast AGC for enhanced dynamic range
- Supports a2dp\avctp\avdtp\avrcp\hfp\spp\smp\att\gap\ gatt\rfcomm\sdp\l2cap profile
- a2dp 1.3.2\avctp 1.4\avdtp 1.3\ avrcp 1.6.2\ hfp 1.8 \spp 1.2\rfcomm 1.1\pnp 1.3\ hid 1.1.1\sdp core5.3\l2cap core 5.3

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Peripherals

- One full speed USB 2.0 OTG controller
- Six multi-function 32-bit timers, support capture and PWM mode
- Three full-duplex basic UART, UART0、
 UART1 support DMA mode
- One hardware IIC interface supports host and device mode
- Three Built-in low power Cap Sense Keys
- LED controller, support 2 LED control by one
- 10-bit ADC for analog sampling
- External wake up/interrupt on all GPIOs
- Crossbar IO support: timer\SPI\SDC\IIC \UART\RDEC\ALINK\PLINK

PMU

- Low voltage LDO and DC-DC for internal digital and analog circuit supply
- Soft-off mode current:

- Build-in LP_Touch off: ≤2uA Build-in LP Touch on: ≤13uA
- Built-in LDO and DC-DC for the core, I/O, Bluetooth and flash
- WBAT is 2.2V to 4.4V
- IOVDD is 2.2V to 3.6V

Packages

QFN32(4mm*4mm)

Temperature

- Operating temperature: -40°C to +85°C
- Storage temperature: -65°C to +150°C

Applications

- Bluetooth Stereo Headsets and Headphones
- Bluetooth Stereo ANC Headsets and Headphones
- Bluetooth ANC TWS Earphones

1 Pin Definition

1.1 Pin Assignment

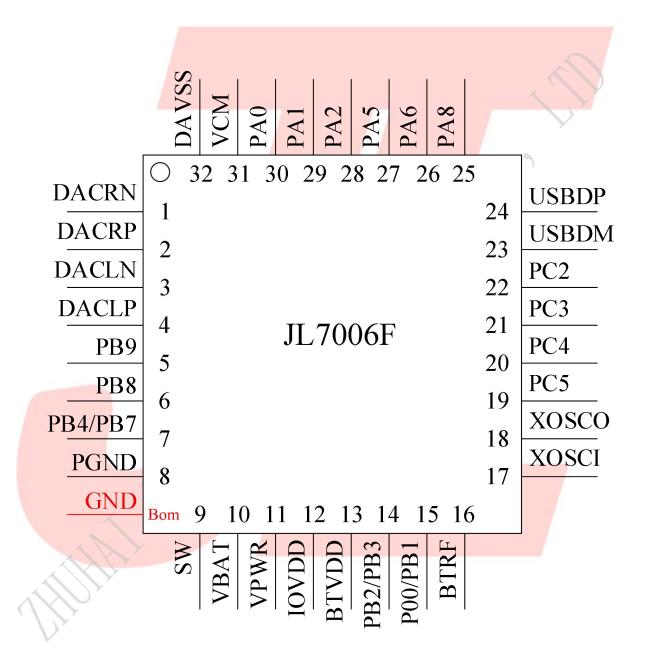


Figure 1-1 JL7006F Package Diagram

1.2 Pin Description

Table 1-1 JL7006F Pin Description

PIN NO.	Name	I/O Type	Drive (mA)	Function	Other Function		
1	DACRN	О	/		Different DAC Right Negative Channel		
2	DACRP	О	/		Different DAC Right Positive Channel		
3	DACLN	0	/		Different DAC Left Negative Channel		
4	DACLP	О	/		Different DAC Left Positive Channel		
	PB9	I/O	2.4~64	GPIO			
5	SDPG	PO	/		SDPG: Supply voltage to SD Card		
6	PB8	I/O	2.4~64	GPIO	MIC1: MIC1 Input Channel; MIC1_P: Different MIC1 Positive; AMUX_B0: Analog Channel B0 L/R Input; UART0RXB: Uart0 Data Input(B); CAP4: Timer4 Capture.		
7	PB7	I/O	2.4~64	GPIO	MIC_BIAS1: MIC1 Bias Output; MIC1_N: Different MIC1 Negative; AMUX_B1: Analog Channel B1 L/R Input; UART0TXB: Uart0 Data Output(B).		
	PB4	I/O	2.4~64	GPIO	LP_TH3: Low Power Touch Channel 3; ADC8: ADC Input Channel 8; TMR2: Timer2 Clock Input; LVD.		
8	PGND	P	1		DCDC Ground		
9	sw	P	1		DCDC switch output, connected to inductor		
10	VBAT	PI	1	/	Power Supply, connect to battery		
	1/1/	PI	/		Charge Power Input;		
11	VPWR	I/O	8	GPIO	High Voltage Resistance I/O; UART0TXC: Uart0 Data Output(C); UART0RXC: Uart0 Data Input(C); PWM3: Timer3 PWM Output; CAP1: Timer1 Capture.		
12	IOVDD	PO	/		IO Power 3.3v		
13	BTVDD	PO	/	GPIO	BT Power		
14	PB2	I/O	2.4~64	GPIO	LP_TH2: Low Power Touch Channel 2; ADC7: ADC Input Channel 7; CAP5: Timer5 Capture; UART2RXC: Uart2 Data Input(C);		

					SPI2DOC: SPI2 Data Out(C).
	PB3	I/O	2.4~64	GPIO	
	EVDD	PO	/		EVDD: Supply voltage to Peripherals
	P00	I/O	8		Test pin
					Long Press Reset;
15				CDIO	LP_TH1: Low Power Touch Channel 1.
13	PB1	I/O	2.4~64	GPIO	UART2TXC: Uart2 Data Output(C).
				(pull up)	ADC6: ADC Input Channel 6;
					SPI2CLKC: SPI2 Clk(C).
16	BTRF	/	/		BT Antenna
17	XOSCI	I	/		XOSC In
18	XOSCO	0	/		XOSC Out
					SD0CLKA: SD0 Clock(A);
					UART2RXD: Uart2 Data Input(D);
19	PC5	I/O	2.4~64	GPIO	SPI1DOB: SPI1 Data Out(B);
19	FC3	1/0	2.4~04	GFIO	ALNK_DAT3(B): Audio Link Data3(B);
					IIC_SDA_B: IIC SDA(B);
					ADC5: ADC Input Channel 5.
					SD0CMDA: SD0 CMD(A);
					UART2TXD: Uart2 Data Output(D);
	PC4		2.4~64		SPI1CLKB: SPI1 Clock(B);
20		I/O		GPIO	ALNK_DAT2(B): Audio Link Data2(B);
					IIC_SCL_B: IIC SCL(B);
A				1	ADC4: ADC Input Channel 4;
1					PWM4: Timer4 PWM Output.
			Y		SD0DATA: SD0 Data(A);
				7	UART0RXD: Uart0 Data Input(D);
V		() /			SPI1DIB: SPI1 Data In(B);
21	PC3	I/O	2.4~64	GPIO	ALNK_LRCK(B): Audio Link Word
					Select(B);
	17/7				IIC_SDA_C: IIC SDA(C);
- 4					TMR3: Timer3 Clock Input;
1	()				ALNK_SCLK(B): Audio Link Serial Clock(B);
22	PC2	I/O	2.4~64	GPIO	IIC_SCL_C: IIC SCL(C);
					UARTOTXD: Uart0 Data Output(D);
					TMR1: Timer1 Clock Input.
					UART1RXD: Uart1 Data Input(D); IIC_SDA_A: IIC SDA(A);
23	USBDM	I/O	4	USB Negative Data	ADC11: ADC Input Channel 11;
23		1/0		OSD Negative Data	SPI2DOB: SPI2 Data Out(B);
					ISP_DI.
24	USBDP	I/O	4	USB Positive Data	UART1TXD: Uart1 Data Output(D);
	OSDDI	1/0	+	OSD I USILIVE Data	OAKTITAD: Oaiti Data Output(D),

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		I	ī	Γ	HG GGL A HG GGL(A)
					IIC_SCL_A: IIC SCL(A);
					ADC10: ADC Input Channel 10;
					SPI2CLKB: SPI2 Clock(B);
					ISP_CLK.
					ALNK_LRCK(A): Audio Link Word
					Select(A);
25	PA8	I/O	2.4~64	GPIO	UART2RXB: Uart1 Data Input(B);
					PLNK_DAT1: PLNK Data1;
					ADC3: ADC Input Channel 3.
					ALNK_DAT3(A): Audio Link Data3(A);
				7	UARTORXA: Uart1 Data Input(A);
					PLNK_DAT0: PLNK Data0;
26	PA6	I/O	2.4~64	GPIO	IIC_SDA_D: IIC SDA(D);
					ADC2: ADC Input Channel 2;
					CAP0: Timer0 Capture;
					SPI2DOA: SPI2 Data Out(A).
			_ A		ALNK_DAT2(A): Audio Link Data2(A);
					UART0TXA: Uart0 Data Output(A);
				14	PLNK_SCLK: PLNK Serial Clock;
27	PA5	I/O	2.4~64	GPIO	IIC_SCL_D: IIC SCL(D);
					ADC1: ADC Input Channel 1;
			/		PWM5: Timer5 PWM Output;
			A.		SPI2CLKA: SPI2 Clock(A).
					ALNK_MCLK(A): ALNK Master Clock(A);
			,	\ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \	MIC_BIAS0: MIC0 Bias Output;
		/.		7 /	MIC0_N: Different MIC0 Negative;
28	PA2	I/O	2.4~64	GPIO	AMUX_A1: Analog Channel A1 L/R Input;
			Y		CAP3: Timer3 Capture;
					UART1RXC: Uart1 Data In(C);
	,				CLKOUT1.
1					MIC0: MIC0 Input Channel;
	1/1/				MICO_P: Different MICO Positive;
29	PA1	I/O	2.4~64	GPIO	AMUX_A0: Analog Channel A0 L/R Input;
	1) r				PWM0: Timer0 PWM Output;
					UART1TXC: Uart1 Data Output(C).
30	PA0	I/O	2.4~64	GPIO	MIC Power Supply
31	VCM	P	/		DAC reference voltage
32	DAVSS	P	/		Analog Ground
/	Bom	P	/		Ground
		l		l	

P: Power or Ground PO:Power Output PI:Power Input I/O:Input or Output I:Input O:Output

2 Electrical Characteristics

2.1 Absolute Maximum Ratings

Table 2-1

Symbol	Parameter	Min	Max	Unit
Topt	Operating temperature	-40	+85	°C
Tstg	Storage temperature	-65	+150	°C
VBAT	Supply Voltage	-0.3	4.5	V
VPWR	Charger Voltage	-0.3	6	V
V _{3.0IO}	3.0V IO Input Voltage (IOVDD)	-0.3	3.6	V

Note: The chip can be damaged by any stress in excess of the absolute maximum ratings listed below.

2.2 PMU Characteristics

Table 2-2

Symbol	Parameter	Min	Тур	Max	Unit	Test Conditions
VBAT	Voltage Input	2.2	3.7	4.4	V	
VPWR	Charger supply Voltage	4.5	5.0	5.5	v	
Normal mode	Ü		^(,	
IOVDD	Voltage output	- /	3.0	9_	V	VBAT = 4.2V, 10mA loading
ממיסו	Loading current	_		100	mA	IOVDD=3.0V@VBAT = 4.2V
BTVDD	Voltage output		1.25	_	V	IOVDD=3.0V, 10mA loading
БІУДД	Loading current	-	/_/	60	mA	BTVDD=1.25V@IOVDD=3.0v
EVDD	Voltage output		1.1	1	V	BTVDD=1.25V, 1mA loading
EADD	Loading current	_	/-/	5	mA	EVDD=1.1V@BTVDD=1.25v
LP mode						
IOVDD	Loading current	3		5	mA	IOVDD=3V@VBAT = 4.2V

2.3 Battery Charge

Table 2-3

Symbol	Parameter	Min	Тур	Max	Unit	Test Conditions
VPWR	Charge Input Voltage	4.5	5	5.5	V	-
W	Charge Voltage	4.15	4.2	4.25	V	VPWR>4.5V
$ m V_{Charge}$	Charge voltage	4.30	4.35	4.40	V	VPWR>4.65V

ICharge	Charge Current	20		200	mA	Charge current at fast charge mode
${ m I}_{ m Trikl}$	Trickle Charge Current	20	45	70	mA	$V_{\mathrm{BAT}}\!\!<\!\!V_{\mathrm{Trikl}}$

2.4 IO Input/Output Electrical Logical Characteristics

Table 2-4

IO input ch	IO input characteristics									
Symbol	Parameter	Min	Тур	Max	Unit	Test Conditions				
V_{IL}	Low-Level Input Voltage	-0.3	_	0.3* IOVDD	V	IOVDD = 3.0V				
$ m V_{IH}$	High-Level Input Voltage	0.7* IOVDD	-	IOVDD+0.3	V	IOVDD= 3.0V				
IO output o	characteristics			- y . /						
V _{OL}	Low-Level Output Voltage	-/	-	0.33	V	IOVDD= 3.0V				
$V_{ m OH}$	High-Level Output Voltage	2.7	- 1	-0	V	IOVDD = 3.0V				

2.5 Internal Resistor Characteristics

Table 2-5

4	Port	Drive(mA)	Internal Pull-Up Resistor	Internal Pull-Down Resistor	Comment	
	PA0~PA8 PB1~PB9 PC2~PC5	2.4 8 26.4 64	10K	10K	1、PB1 default pull up 2、USBDM & USBDP default pull	
	PP0(VPWR), P00	8	10K	10K	Down 3, PP0(VPWR), P00 are high voltage resistance to 5V	
\	USBDP	4	1.5K	15K	4. internal pull-up/pull-down	
	USBDM	4	180K	15K	resistance accuracy ±20%	

2.6 DAC Characteristics

Table 2-6

Parameter	Min	Тур	Max	Unit	Audio Format	Test Conditions
Frequency Response	20	_	20K	Hz	_	Differential Mode
Output Swing		0.55	0.71	Vrms	_	1KHz/0dB
THEAT	_	-78	_	dB	PCM	32 ohm loading
THD+N	_	-69.4	_	dB	SBC	With A-Weighted

C/NI	S/N		100	102	dB	PCM	Filter
5/1\		_	99.5	_	dB	SBC	
Crosstalk		_	-110.0	_	dB	_	
Dynamic Range		_	100.2	-	dB	PCM SBC	Differential Mode 1KHz/-60dB 32 ohm loading With A-Weighted Filter
Noise Floor			6.0		uVrms	_	A-Weighted Filter
DAC Output Power		_	9.5	16.0	mW	-	Differential Mode 32ohm loading

2.7 ADC Characteristics

Table 2-7

Parameter	Min	Тур	Max	Unit	Test Conditions
Dynamic Range		95		dB	Fsample=44.1kHz
		110	X	1	Fin=1KHz 2mVpp Input
SNR	/_	95	11-7	dB	F 1 44 11 II
THD+N	/ _	-72	<u> </u>	dB	Fsample=44.1kHz
Crosstalk	_	-80	_	dB	Fin=1KHz 2Vpp Input

2.8 BT Characteristics

2.8.1 Transmitter

Basic Data Rate

Table 2-8

Parameter N		Min	Тур	Max	Unit	Test Conditions
RF Transmit Power		-	8	10	dBm	
RF Power Control Range			18.2		dB	25°C,
20dB Bandwidth		6	950		KHz	Power Supply
	+2MHz		-40		dBm	VBAT=3.7V
Adjacent Channel	-2MHz		-38		dBm	2441MHz
Transmit Power	+3MHz		-44		dBm	2 Layer Board
	-3MHz		-35		dBm	===, == = = = = = = = = = = = = = = = =

Enhanced Data Rate

Table 2-9

Paramete	Min	Тур	Max	Unit	Test Conditions	
Relative Power			-1.2		dB	
	DEVM RMS	6	11.4		%	25℃,
π/4 DQPSK	DEVM 99%	10	19.7		%	Power Supply
Modulation Accuracy	DEVM Peak		24.8		%	
	+2MHz		-40		dBm	VBAT=3.7V
Adjacent Channel	-2MHz		-38		dBm	2441MHz
Transmit Power	+3MHz		-44		dBm	2 Layer Board
	-3MHz		-35		dBm	

2.8.2 Receiver

Basic Data Rate

Table 2-10

Paramete	Min	Тур	Max	Unit	Test Conditions	
Sensitivit		-92		dBm	25°C	
Co-channel Interferer	ce Rejection		-10		dB	25℃,
	+1MHz		+4		dB	Power Supply
	-1MHz		+2		dB	VBAT=3.7V
Adjacent Channel	+2MHz		+38		dB	2441MHz
Interference Rejection	-2MHz	(1)	+38		dB	DH5
	+3MHz		>+40		dB	2 Layer Board
	-3MHz		+34	No.	dB	2 Layer Board

Enhanced Data Rate

Table 2-11

Parameter		Min	Тур	Max	Unit	Test Conditions
Sensitivit	Sensitivity		-94		dBm	25°0
Co-channel Interference Rejection			-11		dB	25°C,
	+1MHz		+4		dB	Power Supply
	-1MHz		+2		dB	VBAT=3.7V
Adjacent Channel	+2MHz		+38		dB	2441MHz
Interference Rejection	-2MHz		+38		dB	2DH5
	+3MHz		>+40		dB	2 Layer Board
	-3MHz		+34		dB	2 La, or Bourd

2.9 ESD Protection

Table 2-12

Parameter	Тур.	Test pin	Reference standard
Human Body Mode	±4KV	All pins	JEDEC EIA/JESD22-A114
Machine Mode	±200V	All pins	JEDEC EIA/JESD22-A115
Charge Device Model	±1KV	All pins	JEDEC EIA/JESD22-C101F
Latch up	±200mA	All GPIO pins	JEDEC STANDARD NO.78E
	1.5xVopmax	All power pins	JEDEC STANDARD NO./8E

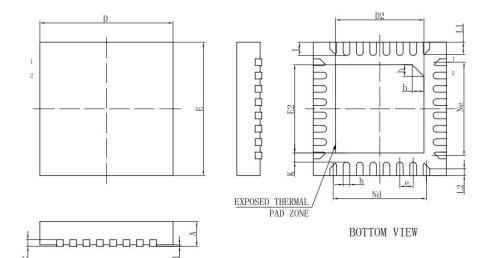
Note: 1.5xVopmax = 1.5 times maximum operating voltage.



Confidential

3 Package Information

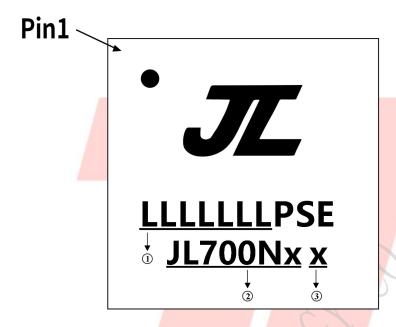
3.1 QFN32_4.0x4.0



SYMBOL	M	ILLIMETI	ER			
SIMBOL	MIN	NOM	MAX			
A	0.70	0.75	0.80			
Al	0	0.02	0.05			
b	0.15	0.20	0.25			
с	0.18	0.20	0.25			
D	3, 90	4.00	4.10			
D2	2, 60	2.65	2.70			
e		0. 40BSC				
Nd		2. 80BSC				
E	3. 90	4.00	4. 10			
E2	2.60	2.65	2.70			
Ne		2. 80BSC				
K	0.20	=	-			
L	0.35	0.40	0.45			
L1	0.30	0.35	0.40			
L2	0.15	0. 20	0.25			
h	0.30	0.35	0.40			
L/F载体尺寸 (MLL)		112*11	2			

Figure 3-1 JL7006F Package

4 IC Marking Information



- 1 LLLLLLL: Production Batch
- ② JL700Nx: Chip Model
- ③ x: Built-in flash size
 - 0: No Flash Memory
 - 2: 2Mbit Flash
 - 4: 4Mbit Flash
 - 8: 8Mbit Flash
 - 6: 16Mbit Flash
 - 3: 32Mbit Flash

5 Solder-Reflow Condition

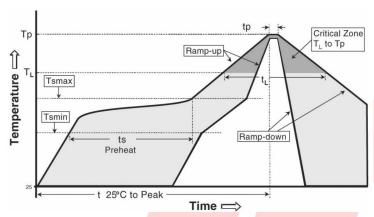


Figure 5-1 Classification Reflow Profile

Classification Profiles

Table 5-1

	Profile Feature	Sn-Pb Eutectic Assembly	Pb-Free Assembly
	Temperature Min (T _{smin})	100℃	150℃
Preheat	Temperature Max (T _{smax})	150℃	200℃
/Soak	Time (ts) from (T _{smin} to T _{smax})	60-120 seconds	60-180 seconds
Average	ramp-up rate (T _{smax} to T _p)	3°C/second max	3 ℃/second max
Liquidous temperature (T _L)		183℃	217℃
Time (t _L) maintained above T _L		60-150 seconds	60-150 seconds
Peak package body temperature (T _p)		See Table 5-2	See Table 5-3
	hin 5°C of actual pperature (tp)²	10-30 seconds	20-40 seconds
Ramp-down rate (T _p to T _L)		6°C/second max	6°C/second max
Time 25°	C to peak temperature	6 minutes max	8 minutes max

Note 1: All temperatures refer to topside of the package, measured on the package body surface.

Note 2: Time within 5° C of actual peak temperature (tp) specified for the reflow profiles is a "supplier" minimum and "user" maximum.

SnPb - Classification Temperature

Table 5-2

Package	Volume mm ³	Volume mm ³
Thickness	< 350	≥ 350
<2.5 mm	240 +0/-5°C	225 +0/-5°C
≥2.5 mm	225 +0/-5°C	225 +0/-5℃

Pb-free - Classification Temperature

Table 5-3

Package Thickness	Volume mm ³ < 350	Volume mm ³ 350 - 2000	Volume mm ³ > 2000
< 1.6mm	260°C	260℃	260°C
1.6 mm - 2.5mm	260℃	250℃	245℃
> 2.5mm	250℃	245°C	245℃



6 Revision History

Date	Revision	Description
2022.05.14	V1.0	Initial Release
2022.07.13	V1.1	Update Soft-off mode current consumption

